

PEMB18; PUMB18

PNP/PNP resistor-equipped transistors;
R1 = 4.7 k Ω , R2 = 10 k Ω

Rev. 5 — 21 December 2011

Product data sheet

1. Product profile

1.1 General description

PNP/PNP double Resistor-Equipped Transistors (RET) in Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

| Type number | Package | | NPN/PNP complement | NPN/NPN complement | Package configuration |
|-------------|---------|-------|--------------------|--------------------|---------------------------|
| | NXP | JEITA | | | |
| PEMB18 | SOT666 | - | PEMD18 | PEMH18 | ultra small and flat lead |
| PUMB18 | SOT363 | SC-88 | PUMD18 | PUMH18 | very small |

1.2 Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs
- AEC-Q101 qualified

1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications

1.4 Quick reference data

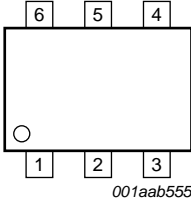
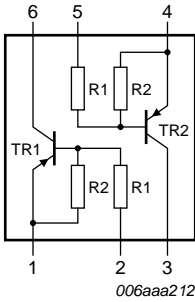
Table 2. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|---------------------------|------------|-----|-----|------|------------|
| Per transistor | | | | | | |
| V _{CEO} | collector-emitter voltage | open base | - | - | -50 | V |
| I _O | output current | | - | - | -100 | mA |
| R1 | bias resistor 1 (input) | | 3.3 | 4.7 | 6.1 | k Ω |
| R2/R1 | bias resistor ratio | | 1.7 | 2.1 | 2.6 | |



2. Pinning information

Table 3. Pinning

| Pin | Description | Simplified outline | Graphic symbol |
|-----|------------------------|--|--|
| 1 | GND (emitter) TR1 |  001aab555 |  006aaa212 |
| 2 | input (base) TR1 | | |
| 3 | output (collector) TR2 | | |
| 4 | GND (emitter) TR2 | | |
| 5 | input (base) TR2 | | |
| 6 | output (collector) TR1 | | |

3. Ordering information

Table 4. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| PEMB18 | - | plastic surface-mounted package; 6 leads | SOT666 |
| PUMB18 | SC-88 | plastic surface-mounted package; 6 leads | SOT363 |

4. Marking

Table 5. Marking codes

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| PEMB18 | 6A |
| PUMB18 | B8* |

[1] * = placeholder for manufacturing site code

5. Limiting values

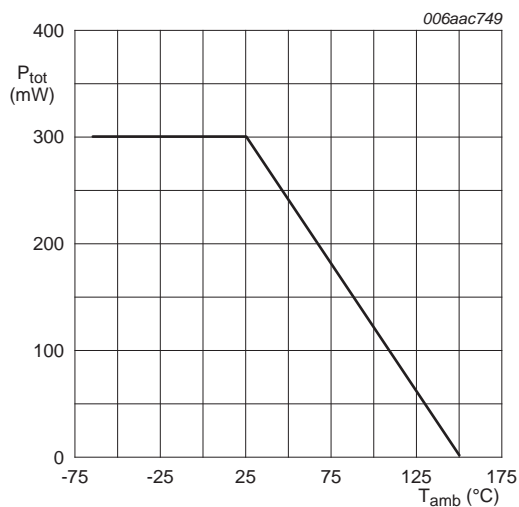
Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------|---------------------------|--|--------|------|------|
| Per transistor | | | | | |
| V _{CBO} | collector-base voltage | open emitter | - | -50 | V |
| V _{CEO} | collector-emitter voltage | open base | - | -50 | V |
| V _{EBO} | emitter-base voltage | open collector | - | -7 | V |
| V _I | input voltage | | | | |
| | positive | | - | +7 | V |
| | negative | | - | -20 | V |
| I _O | output current | | - | -100 | mA |
| I _{CM} | peak collector current | single pulse; t _p ≤ 1 ms | - | -100 | mA |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | | | |
| | PEMB18 (SOT666) | | [1][2] | 200 | mW |
| | PUMB18 (SOT363) | | [1] | 200 | mW |
| Per device | | | | | |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | | | |
| | PEMB18 (SOT666) | | [1][2] | 300 | mW |
| | PUMB18 (SOT363) | | [1] | 300 | mW |
| T _j | junction temperature | | - | 150 | °C |
| T _{amb} | ambient temperature | | -65 | +150 | °C |
| T _{stg} | storage temperature | | -65 | +150 | °C |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.



FR4 PCB, standard footprint

Fig 1. Per device: Power derating curve for SOT363 (SC-88) and SOT666

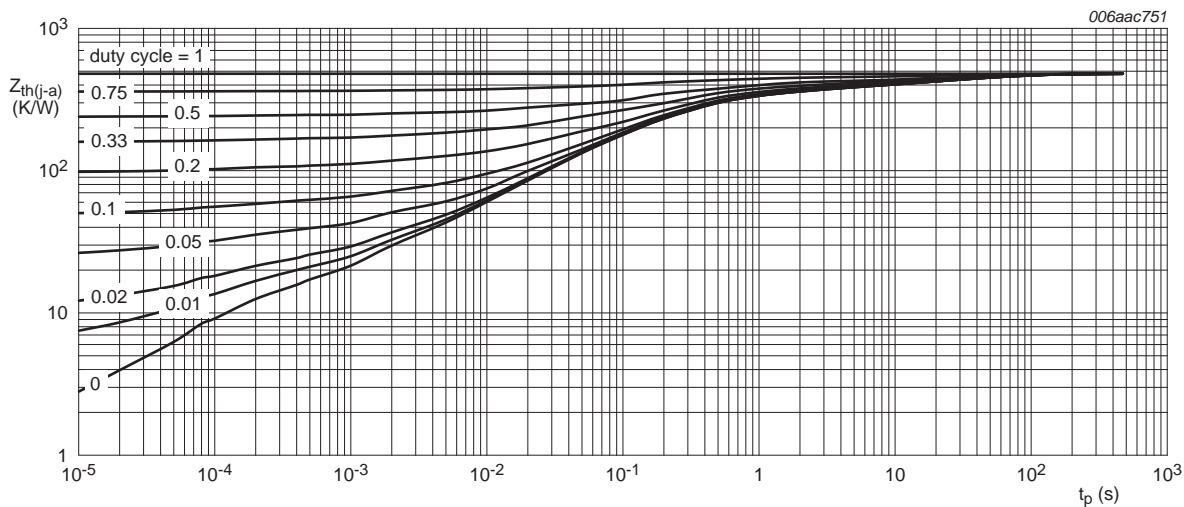
6. Thermal characteristics

Table 7. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|---|-------------|--------|-----|-----|------|
| Per transistor | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | | | |
| | PEMB18 (SOT666) | | [1][2] | - | 625 | K/W |
| | PUMB18 (SOT363) | | [1] | - | 625 | K/W |
| Per device | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | | | |
| | PEMB18 (SOT666) | | [1][2] | - | 417 | K/W |
| | PUMB18 (SOT363) | | [1] | - | 417 | K/W |

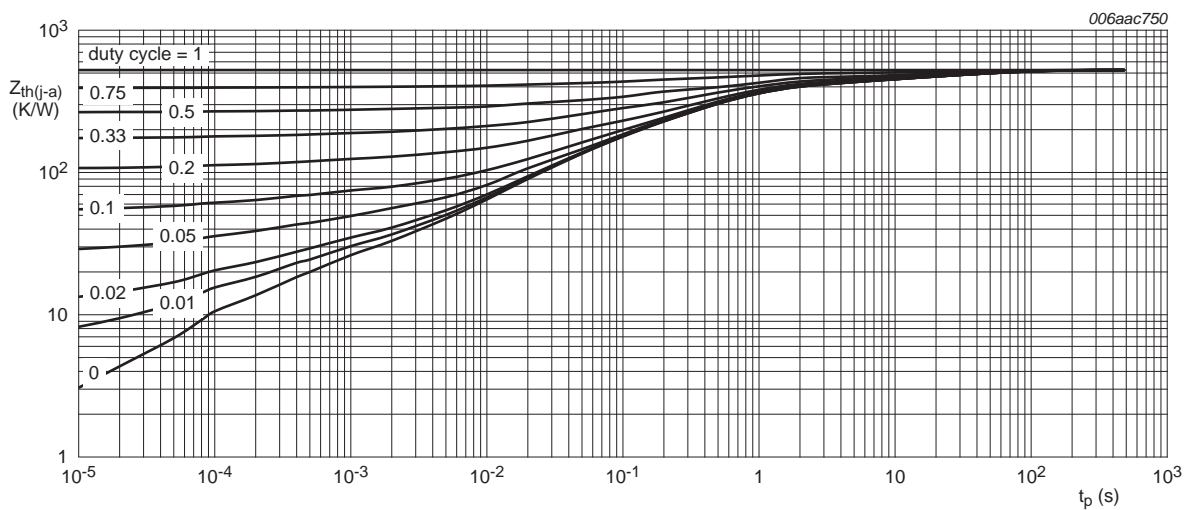
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.



FR4 PCB, standard footprint

Fig 2. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration for PEMB18 (SOT666); typical values



FR4 PCB, standard footprint

Fig 3. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration for PUMB18 (SOT363); typical values

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|--------------------------------------|--|------|------|------|---------------|
| Per transistor | | | | | | |
| I_{CBO} | collector-base cut-off current | $V_{CB} = -50\text{ V}$; $I_E = 0\text{ A}$ | - | - | -100 | nA |
| I_{CEO} | collector-emitter cut-off current | $V_{CE} = -30\text{ V}$; $I_B = 0\text{ A}$ | - | - | -1 | μA |
| | | $V_{CE} = -30\text{ V}$; $I_B = 0\text{ A}$; $T_j = 150\text{ }^{\circ}\text{C}$ | - | - | -5 | μA |
| I_{EBO} | emitter-base cut-off current | $V_{EB} = -5\text{ V}$; $I_C = 0\text{ A}$ | - | - | -600 | μA |
| h_{FE} | DC current gain | $V_{CE} = -5\text{ V}$; $I_C = -10\text{ mA}$ | 50 | - | - | |
| V_{CEsat} | collector-emitter saturation voltage | $I_C = -10\text{ mA}$; $I_B = -0.5\text{ mA}$ | - | - | -100 | mV |
| $V_{I(off)}$ | off-state input voltage | $V_{CE} = -5\text{ V}$; $I_C = -100\text{ }\mu\text{A}$ | - | -0.9 | -0.3 | V |
| $V_{I(on)}$ | on-state input voltage | $V_{CE} = -0.3\text{ V}$; $I_C = -20\text{ mA}$ | -2.5 | -1.5 | - | V |
| R1 | bias resistor 1 (input) | | 3.3 | 4.7 | 6.1 | k Ω |
| R2/R1 | bias resistor ratio | | 1.7 | 2.1 | 2.6 | |
| C_c | collector capacitance | $V_{CB} = -10\text{ V}$; $I_E = i_e = 0\text{ A}$; $f = 1\text{ MHz}$ | - | - | 3 | pF |
| f_T | transition frequency | $V_{CE} = -5\text{ V}$; $I_C = -10\text{ mA}$; [1] $f = 100\text{ MHz}$ | - | 180 | - | MHz |

[1] Characteristics of built-in transistor

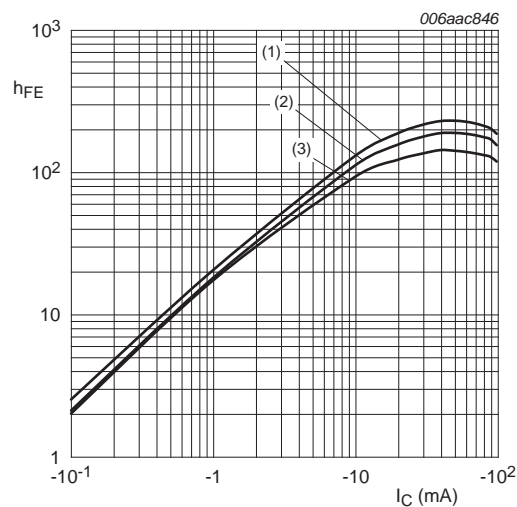


Fig 4. DC current gain as a function of collector current; typical values

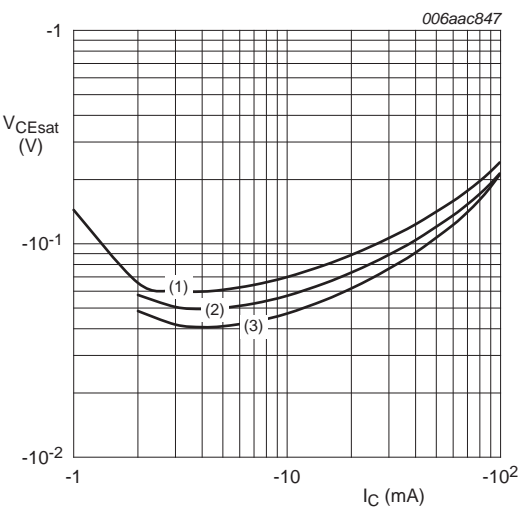


Fig 5. Collector-emitter saturation voltage as a function of collector current; typical values

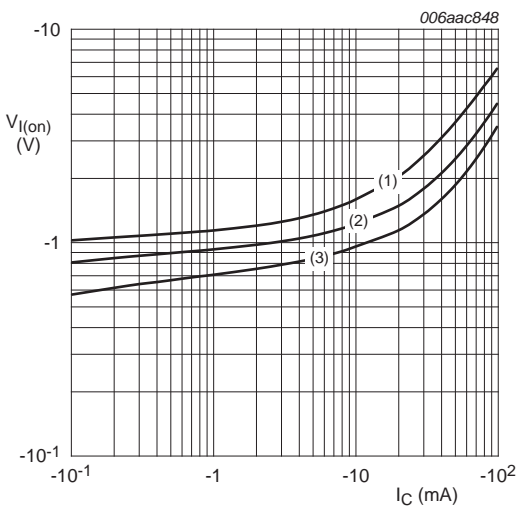


Fig 6. On-state input voltage as a function of collector current; typical values

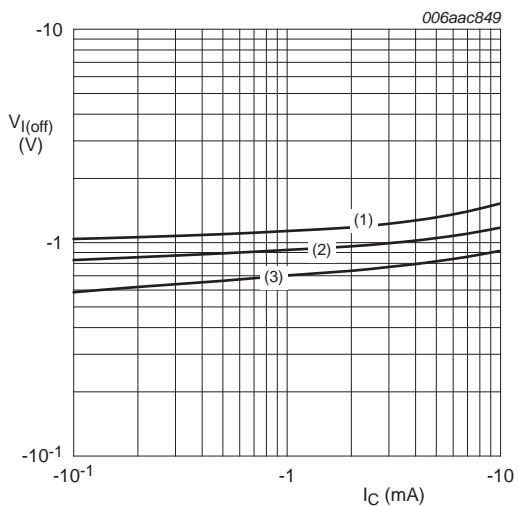
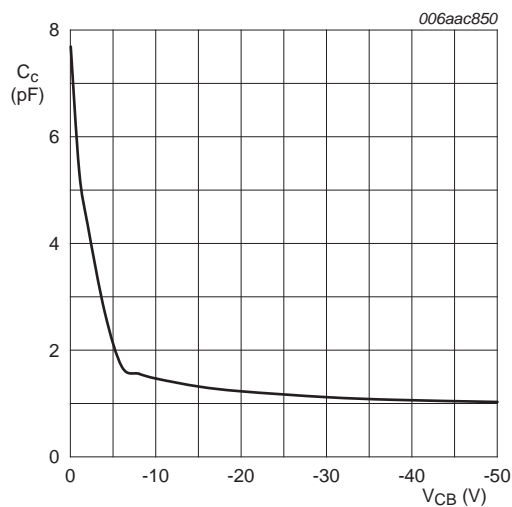
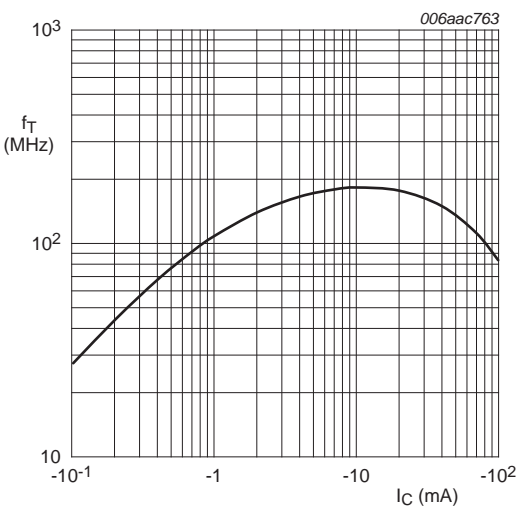


Fig 7. Off-state input voltage as a function of collector current; typical values



$f = 1 \text{ MHz}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$

Fig 8. Collector capacitance as a function of collector-base voltage; typical values



$V_{CE} = -5 \text{ V}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$

Fig 9. Transition frequency as a function of collector current; typical values of built-in transistor

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline

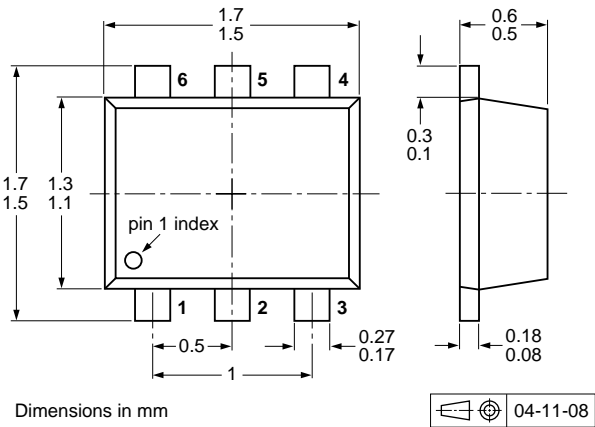


Fig 10. Package outline PEMB18 (SOT666)

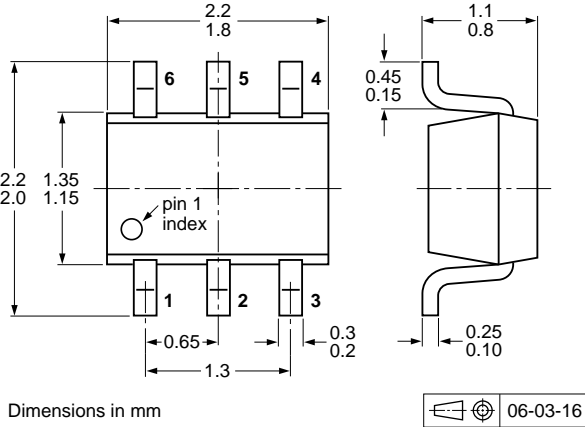


Fig 11. Package outline PUMB18 (SOT363)

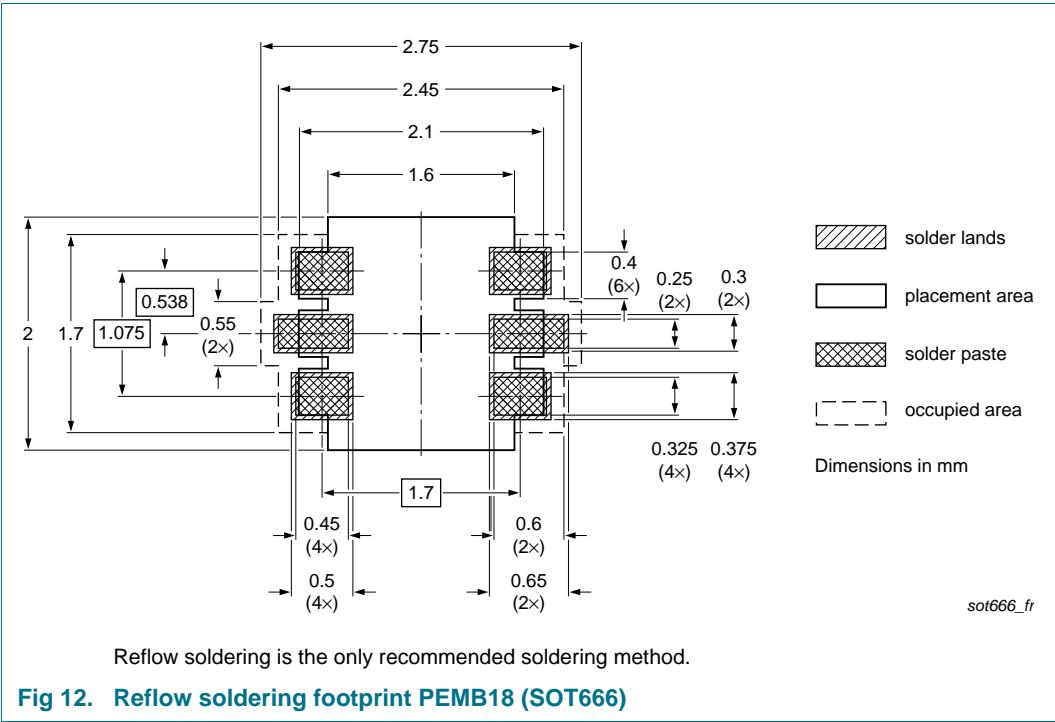
10. Packing information

Table 9. Packing methods
The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

| Type number | Package | Description | Packing quantity | | | |
|-------------|---------|---|------------------|------|------|-------|
| | | | 3000 | 4000 | 8000 | 10000 |
| PEMB18 | SOT666 | 2 mm pitch, 8 mm tape and reel | - | - | -315 | - |
| | | 4 mm pitch, 8 mm tape and reel | - | -115 | - | - |
| PUMB18 | SOT363 | 4 mm pitch, 8 mm tape and reel; T1 ^[2] | -115 | - | - | -135 |
| | | 4 mm pitch, 8 mm tape and reel; T2 ^[3] | -125 | - | - | -165 |

- [1] For further information and the availability of packing methods, see [Section 14](#).
[2] T1: normal taping
[3] T2: reverse taping

11. Soldering



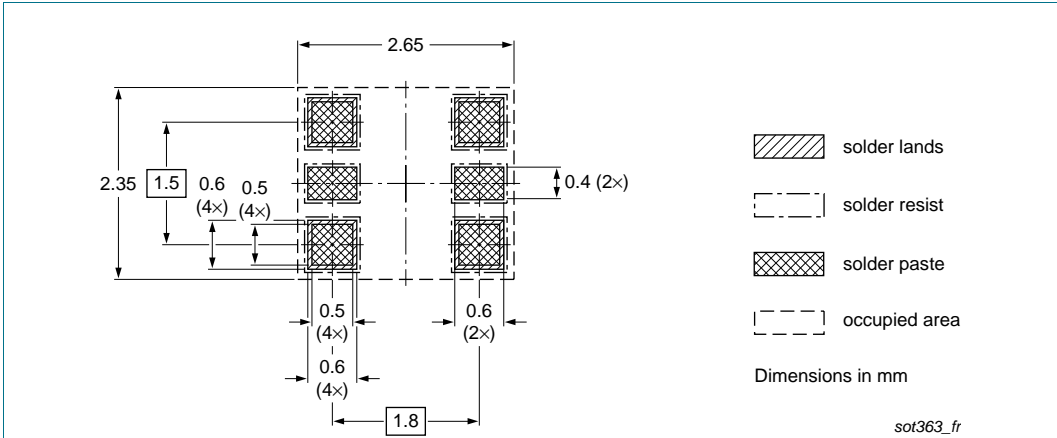


Fig 13. Reflow soldering footprint PUMB18 (SOT363)

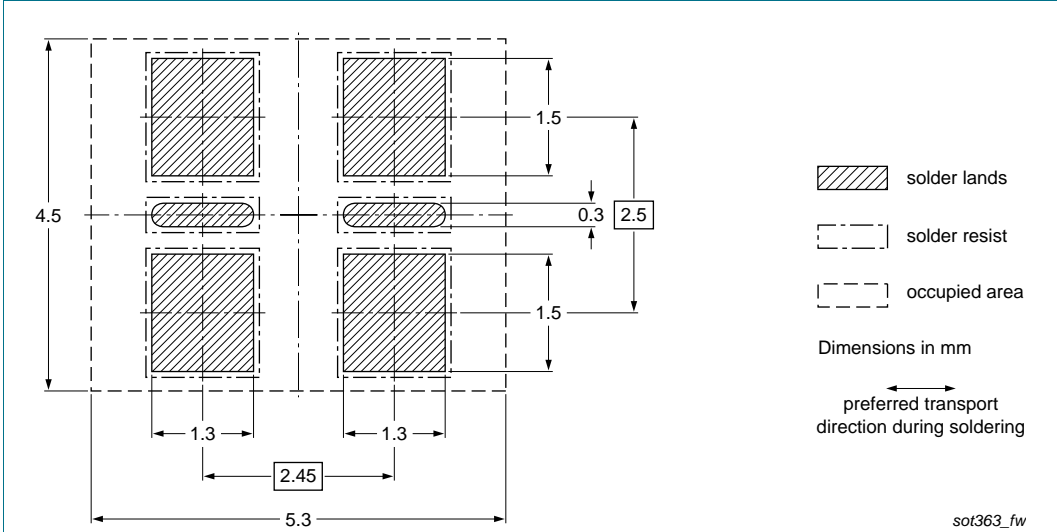


Fig 14. Wave soldering footprint PUMB18 (SOT363)

12. Revision history

Table 10. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---|--------------|-----------------------|---------------|-------------------|
| PEMB18_PUMB18 v.5 | 20111221 | Product data sheet | - | PEMB18_PUMB18 v.4 |
| Modifications: <ul style="list-style-type: none"> • Section 1 "Product profile": updated • Section 4 "Marking": updated • Figure 1 to 3, 8 and 9: added • Section 6 "Thermal characteristics": updated • Figure 4 to 7: updated • Table 8 "Characteristics": I_{CEO} and V_{CEsat} updated, f_T added • Section 8 "Test information": added • Section 11 "Soldering": added • Section 13 "Legal information": updated | | | | |
| PEMB18_PUMB18 v.4 | 20090901 | Product data sheet | - | PEMB18_PUMB18 v.3 |
| PEMB18_PUMB18 v.3 | 20050708 | Product data sheet | - | PEMB18_PUMB18 v.2 |
| PEMB18_PUMB18 v.2 | 20050202 | Product data sheet | - | PUMB18 v.1 |
| PUMB18 v.1 | 20031003 | Product specification | - | - |

13. Legal information

13.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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